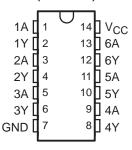
- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>
- EPIC™ (Enhanced-Performance Implanted CMOS) Process
- Operating Range 2-V to 5.5-V V<sub>CC</sub>
- ESD Protection Exceeds 1500 V Per MIL-STD-833, Method 3015; Exceeds 150 V Using Machine Model (C = 200 pF, R = 0)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

#### D OR PW PACKAGE (TOP VIEW)



## description/ordering information

The SN74AHC04 contains six independent inverters. This device performs the Boolean function  $Y = \overline{A}$ .

#### **ORDERING INFORMATION**

TA	PACKA	\GE <sup>‡</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
5500 1- 40500	SOIC - D	Tape and reel	SN74AHC04MDREP	AHC04MEP
−55°C to 125°C	TSSOP - PW	Tape and reel	SN74AHC04MPWREP	AHC04EP

<sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

## FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н



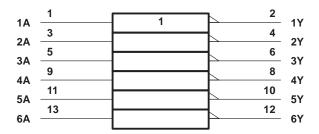
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TEXAS INSTRUMENTS

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## logic symbol<sup>†</sup>



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### logic diagram, each inverter (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 7 V
Output voltage range, V <sub>O</sub> (see Note 1)	$\dots$ -0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, $I_{ K }(V_{ C } < 0)$	–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package	86°C/W
PW package	113°C/W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



## recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vсс	Supply voltage		2	5.5	V
		V <sub>CC</sub> = 2 V	1.5		
ViH	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		V
	Low-level input voltage  Input voltage Output voltage High-level output current  Low-level output current  Input transition rise or fall rate	V <sub>CC</sub> = 5.5 V	3.85		
		V <sub>CC</sub> = 2 V		0.5	
٧ <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 3 V		0.9	V
		V <sub>CC</sub> = 5.5 V		1.65	
٧ <sub>I</sub>	Input voltage		0	5.5	V
Vo	Output voltage		0	VCC	V
		V <sub>CC</sub> = 2 V		-50	μΑ
lOH	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4	A
		$V_{CC} = 5 V \pm 0.5 V$		-8	mA
		V <sub>CC</sub> = 2 V		50	μΑ
lOL	Low-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4	A
		$V_{CC} = 5 V \pm 0.5 V$		8	mA
41/4	Level transfer with a state of fall and	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		100	0./
Δt/Δv	Input transition rise or fall rate $V_{CC} = 5 \text{ V} \pm 0.5$			20	ns/V
TA	Operating free-air temperature		-55	125	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DARAMETER	TTOT COURTIONS	.,	T	λ = 25°C	;		MAY	
PARAMETER	TEST CONDITIONS	TIONS V <sub>CC</sub>		TYP	MAX	MIN	MAX	UNIT
		2 V	1.9	2		1.9		
	I <sub>OH</sub> = -50 μA	3 V	2.9	3		2.9		
VOH		4.5 V	4.4	4.5		4.4		V
	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		
	I <sub>OH</sub> = -8 mA	4.5 V	3.94			3.8		
		2 V			0.1		0.1	
	I <sub>OL</sub> = 50 μA	3 V			0.1		0.1	
V <sub>OL</sub>		4.5 V			0.1		0.1	V
	I <sub>OL</sub> = 4 mA	3 V			0.36		0.5	
	I <sub>OL</sub> = 8 mA	4.5 V			0.36		0.5	
lį	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		20	μΑ
Ci	$V_I = V_{CC}$ or GND	5 V		2	10			pF

## switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	λ = 25°C	;			
	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
t <sub>PLH</sub>		Υ	C <sub>L</sub> = 15 pF		5	8.9	1	10.5	
t <sub>PHL</sub>	А				5	8.9	1	10.5	ns
t <sub>PLH</sub>	^	V	C. F0.pF		7.5	11.4	1	13	
<sup>t</sup> PHL	А	Ť	$C_L = 50 pF$		7.5	11.4	1	13	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	չ = 25°C	;	BAINI	MAY	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH		V	0 45 - 5		3.8	5.5	1	6.5	
<sup>t</sup> PHL	А	Y	C <sub>L</sub> = 15 pF		3.8	5.5	1	6.5	ns
<sup>t</sup> PLH	٨	V	C: - 50 pF		5.3	7.5	1	8.5	20
<sup>t</sup> PHL	А	I	C <sub>L</sub> = 50 pF		5.3	7.5	1	8.5	ns

## noise characteristics, $V_{CC}$ = 5 V, $C_L$ = 50 pF, $T_A$ = 25°C (see Note 4)

	PARAMETER	MIN	TYP	MAX	UNIT
V <sub>OL(P)</sub>	Quiet output, maximum dynamic V <sub>OL</sub>		0.4		V
V <sub>OL(V)</sub>	Quiet output, minimum dynamic V <sub>OL</sub>		-0.4		V
VOH(V)	Quiet output, minimum dynamic VOH		4.8		V
VIH(D)	High-level dynamic input voltage	3.5			V
V <sub>IL(D)</sub>	Low-level dynamic input voltage			1.5	V

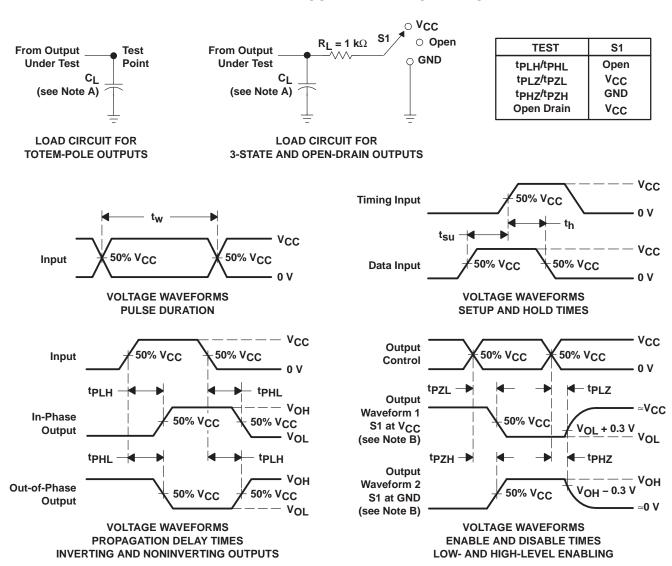
NOTE 4: Characteristics are for surface-mount packages only.



## operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	No load, f = 1 MHz	12	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 3$  ns,  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74AHC04MDREP	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC04MEP
SN74AHC04MDREP.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC04MEP
SN74AHC04MPWREP	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC04EP
SN74AHC04MPWREP.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC04EP
V62/03646-01XE	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC04EP
V62/03646-01YE	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC04MEP

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.





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#### OTHER QUALIFIED VERSIONS OF SN74AHC04-EP:

• Automotive : SN74AHC04-Q1

• Military : SN54AHC04

#### NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

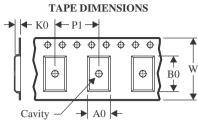
• Military - QML certified for Military and Defense Applications

## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

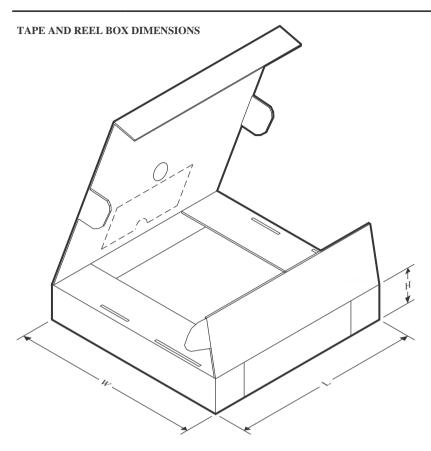
#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC04MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHC04MPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC04MDREP	SOIC	D	14	2500	340.5	336.1	32.0
SN74AHC04MPWREP	TSSOP	PW	14	2000	353.0	353.0	32.0

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